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## IEC 61249-8-8:1997 Materials for interconnection structures - Part 8: Sectional specification set for non-conductive films and coatings - Section 8: Temporary polymer coatings

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### Abbreviation

IEC 61249-8-8:1997

### Valid from

24/06/1997

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### Information provider

International Electrotechnical Commission

### Author

International Electrotechnical Commission

### Information type

IEC Standard

### Format

PDF

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### Cited By

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### Description

This part of IEC 61249 provides requirements for the qualification of temporary solder resist coatings. Requirements stated in this specification will also have some limited validity for assessing the suitability of printed boards which are supplied with peelable solder masks.

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- [BS EN 115-1:2008](#)

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